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(71) Applicant: **INTERNATIONAL BUSINESS MACHINES CORPORATION** [US/US]; New Orchard Road, Armonk, New York, 10504 (US).

(71) Applicants (for MG only): **IBM UNITED KINGDOM LIMITED** [GB/GB]; PO Box 41, North Harbour, Portsmouth Hampshire PO6 3AU (GB). **IBM (CHINA) INVESTMENT COMPANY LIMITED** [CN/CN]; 25/F, Pangu Plaza, No.27, Central North 4th Ring Road, Chaoyang District, Beijing 100101 (CN).

(72) Inventor: **LEOBANDUNG, Effendi**; IBM Corporation, 1101 Kitchawan Road, PO Box 218, Yorktown Heights, New York 10598-0218 (US).

(74) Agent: **WILLIAMS, Julian**; IBM United Kingdom Limited, Intellectual Property Law, Hursley Park, Hursley, Winchester Hampshire SO21 2JN (GB).

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(54) Title: INTERPOSER-LESS MULTI-CHIP MODULE

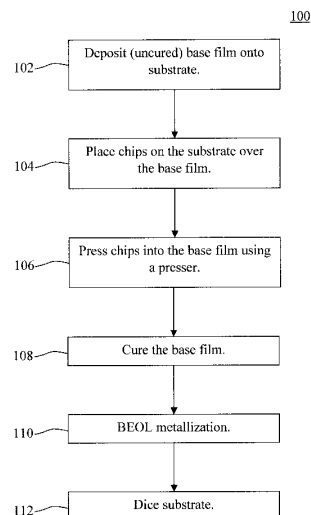


FIG. 1

(57) Abstract: Interposer-less multi-chip module are provided. In one aspect, an interposer-less multi-chip module includes: a substrate; a base film disposed on the substrate; and chips pressed into the base film, wherein top surfaces of the chips are coplanar. For instance, the chips can have varying thicknesses and are pressed into the base film to different depths such that top surfaces of the chips are coplanar. An interconnect layer having back-end-of line (BEOL) metal wiring can be present on the wafer over the chips. Methods of forming an interposer-less multi-chip module are also provided.

[Continued on next page]

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